## **High Voltage Power Transistors**

### **DPAK for Surface Mount Applications**

Designed for line operated audio output amplifier, switchmode power supply drivers and other switching applications.

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Electrically Similar to Popular MJE340 and MJE350
- Epoxy Meets UL 94 V-0 @ 0.125 in
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	300	Vdc
Collector-Base Voltage	V <sub>CB</sub>	300	Vdc
Emitter-Base Voltage	V <sub>EB</sub>	3	Vdc
Collector Current – Continuous	Ic	0.5	Adc
Collector Current – Peak	I <sub>CM</sub>	0.75	Adc
Total Power Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	15 0.12	W W/°C
Total Power Dissipation (Note 1)  @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.56 0.012	W W/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-65 to +150	°C
ESD – Human Body Model MJD340 (NPN) MJD350 (PNP)	НВМ	3B 2	V
ESD – Machine Model MJD340 (NPN) MJD350 (PNP)	MM	M4 M4	V

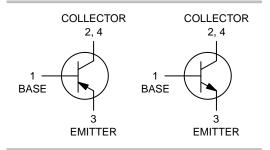
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



#### ON Semiconductor®

www.onsemi.com

### SILICON **POWER TRANSISTORS** 0.5 AMPERE 300 VOLTS, 15 WATTS





**DPAK CASE 369C** STYLE 1

#### **MARKING DIAGRAM**



= Assembly Location

= Year

WW = Work Week

= Device Code J3x0 x = 4 or 5

= Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

<sup>1.</sup> These ratings are applicable when surface mounted on the minimum pad sizes recommended.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	8.33	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	80	°C/W
Leading Temperature for Soldering Purpose	TL	260	°C

<sup>2.</sup> These ratings are applicable when surface mounted on the minimum pad sizes recommended.

### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS		•		1
Collector–Emitter Sustaining Voltage (Note 3) (I <sub>C</sub> = 1 mA, I <sub>B</sub> = 0)	V <sub>CEO(sus)</sub>	300	_	V
Collector Cutoff Current (V <sub>CB</sub> = 300 V, I <sub>E</sub> = 0)	I <sub>CEO</sub>	-	0.1	mA
Emitter Cutoff Current $(V_{BE} = 3 \text{ V, } I_{C} = 0)$	I <sub>EBO</sub>	_	0.1	mA
ON CHARACTERISTICS (Note 3)	•			
DC Current Gain (I <sub>C</sub> = 50 mA, V <sub>CE</sub> = 10 V)	h <sub>FE</sub>	30	240	_
Collector–Emitter Saturation Voltage (I <sub>C</sub> = 100 mA, I <sub>B</sub> = 10 mA)	V <sub>CE(sat)</sub>	_	1	V
Base–Emitter On Voltage (I <sub>C</sub> = 1 A, V <sub>CE</sub> = 10 V)	V <sub>BE(on)</sub>	-	1.5	V
DYNAMIC CHARACTERISTICS	•	•		•
Current Gain – Bandwidth Product (I <sub>C</sub> = 50 mA, V <sub>CE</sub> = 10 V, f = 10 MHz)	f <sub>T</sub>	10	_	MHz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2%.

### **TYPICAL CHARACTERISTICS**

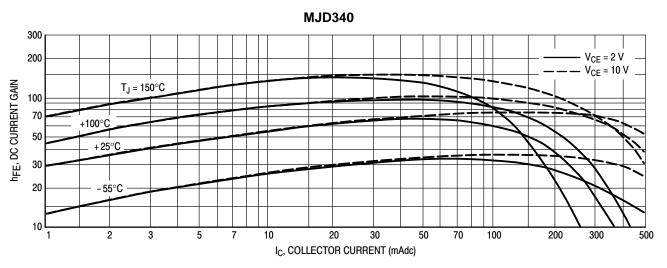


Figure 1. DC Current Gain

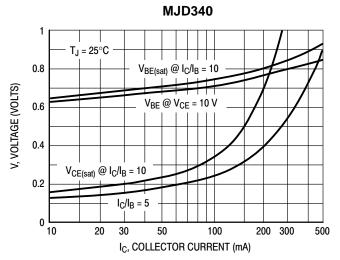
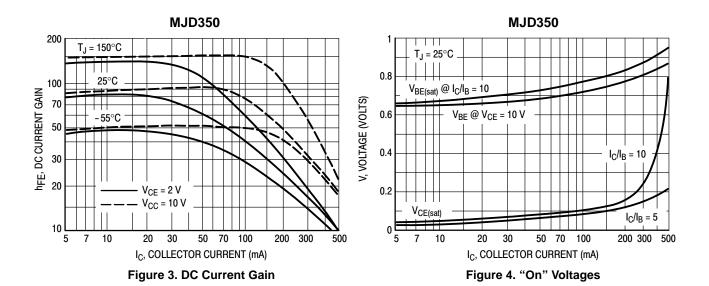


Figure 2. "On" Voltages



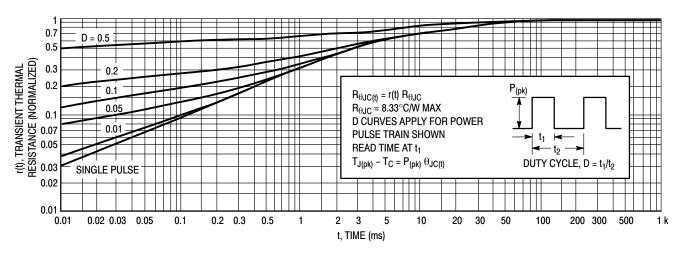


Figure 5. Thermal Response

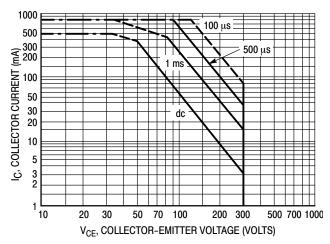


Figure 6. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C - V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 6 is based on  $T_{J(pk)} = 150^{\circ}C$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \le 150^{\circ}C$ .  $T_{J(pk)}$  may be calculated from the data in Figure 5. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

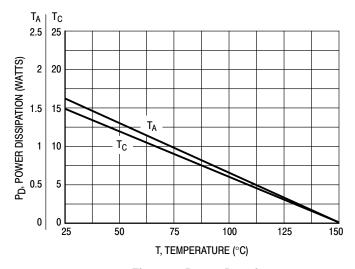


Figure 7. Power Derating

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MJD340G	DPAK (Pb-Free)	75 Units / Rail
MJD340RLG	DPAK (Pb-Free)	1,800 / Tape & Reel
MJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD340T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
MJD350G	DPAK (Pb-Free)	75 Units / Rail
MJD350T4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NJVMJD350T4G	DPAK (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

В

NOTE 7

|  $\oplus$  | 0.005 (0.13) lacktriangledown C

Ħ

Α1

- h3

Ո

**TOP VIEW** 

L3

b2 e

L2 GAUGE

### **DPAK (SINGLE GAUGE)** CASE 369C **ISSUE F** SCALE 1:1 Α

DETAIL A

C SEATING

C-

SIDE VIEW

**DATE 21 JUL 2015** 

#### NOTES:

z

**BOTTOM VIEW** 

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
  5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.

  6. DATUMS A AND B ARE DETERMINED AT DATUM
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51 BSC	
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

#### ALTERNATE CONSTRUCTIONS **DETAIL A** ROTATED 90° CW **GENERIC** STYLE 1: STYLE 2: STYLE 3: STYLE 4: STYLE 5: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE PIN 1. GATE 2. DRAIN

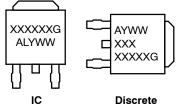
Z

**BOTTOM VIEW** 

С

3. EMITTE 4. COLLE	ER .	3. SOURCE 4. DRAIN	3. AN	ODE THODE	3. GATE 4. ANODE	3.	CATHODE ANODE
STYLE 6: PIN 1. MT1 2. MT2 3. GATE	STYLE 7: PIN 1. GATE 2. COLLE 3. EMITT	PII ECTOR	'LE 8: N 1. N/C 2. CATHODE 3. ANODE		ODE THODE SISTOR ADJUS	2.	0: CATHODE ANODE CATHODE
4. MT2	<ol><li>COLLE</li></ol>	ECTOR	<ol><li>CATHODE</li></ol>	4. CA	THODE	4.	ANODE

# **MARKING DIAGRAM\***



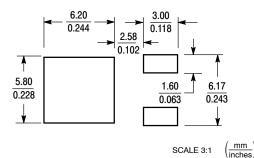
XXXXXX = Device Code = Assembly Location Α L = Wafer Lot Υ = Year WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking.

= Pb-Free Package

G

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON10527D	Electronic versions are uncontrolled except when accessed directly from the Document Reposit Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	DPAK (SINGLE GAUGE)		PAGE 1 OF 1	

ON Semiconductor and un are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others

ON Semiconductor and the are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor and see no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

ON Semiconductor Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

# **Mouser Electronics**

**Authorized Distributor** 

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

### **ON Semiconductor:**

<u>MJD340G MJD340RL MJD340RLG MJD340T4G MJD340T4G MJD350G MJD350T4G </u>